



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20170118005
Datasheet for ISO5851
Information Only**

Date: February 14, 2017
To: Newark/Farnell PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

**Information Only
Attachments**

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
ISO5851DW	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170118005	PCN Date:	Feb. 14, 2017
Title:	Datasheet for ISO5851		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



ISO5851

SLLSEN5B – JUNE 2015 – REVISED JANUARY 2017

Changes from Revision A (June 2015) to Revision B

Page

• Changed the Title From: "Active Safety Features" To: Active Protection Features"	1
• Changed Feature From: Surge Immunity 12800- V_{PK} (according to IEC 61000-4-5) To: Isolation Surge Withstand Voltage 12800- V_{PK}	1
• Added the <i>Power Ratings</i> table	7
• Moved <i>Insulation Characteristics</i> to the <i>Specifications</i>	7
• Changed the Test Conditions and values for q_{pd} in <i>Insulation Characteristics</i>	7
• Changed R_{θ} From: $100^{\circ}\text{C} \leq T_A \leq \text{max}$ To: $100^{\circ}\text{C} \leq T_A \leq 125^{\circ}\text{C}$ in the <i>Insulation Characteristics</i>	7
• Moved <i>Safety-Related Certifications</i> to the <i>Specifications</i>	8
• Changed the CSA status from planned to certified	8
• Moved <i>Safety Limiting Values</i> to the <i>Specifications</i>	8
• Added the <i>Reinforced High-Voltage Capacitor Life Time Projection</i> figure to <i>Insulation Characteristics Curves</i>	11
• Changed the <i>Thermal Derating Curve for Limiting Current per VDE</i> figure and Added the <i>Thermal Derating Curve for Limiting Power per VDE</i> figure	11
• Added the I_{CC1} <i>Supply Current vs Temperature</i> figure to the <i>Typical Characteristics</i>	13
• Changed the <i>OUT Propagation Delay, Non-Inverting Configuration</i> figure	18
• Changed the <i>OUT Propagation Delay, Inverting Configuration</i> figure	18
• Added text ", but connecting CLAMP output of the gate driver to the IGBT gate is also not an issue." to <i>Supply and Active Miller Clamp</i>	21
• Changed the second paragraph of the <i>Typical Applications</i>	23
• Added text "and \overline{RST} input signal" to <i>Design Requirements</i>	24
• Deleted text " and a 220-pF filtering capacitor." from <i>Recommended ISO5851 Application Circuit</i>	25
• Deleted text "thereby, providing protection against further catastrophic failures." From: the <i>Global-Shutdown and Reset</i> section	27
• Changed the <i>Normal Operation - Bipolar Supply</i> and <i>Normal Operation - Unipolar Supply</i> figures	32
• Changed the <i>PCB Material</i> section	33
• Changed the <i>Electrostatic Discharge Caution</i>	34

The datasheet number will be changing.

Device Family	Change From:	Change To:
ISO5851	SLLSEN5A	SLLSEN5B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/ISO5851>

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

ISO5851DW	ISO5851DWR		
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com